

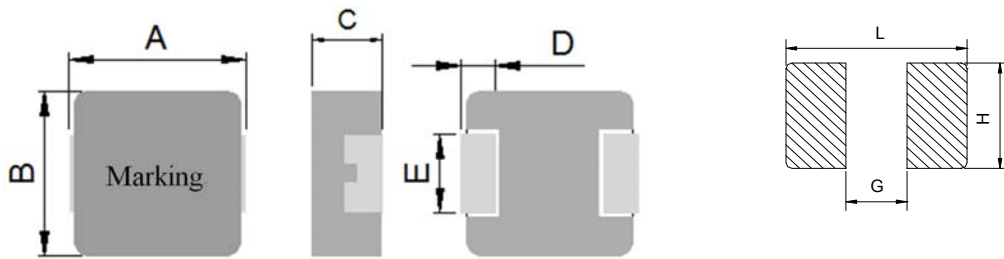
1. Part No. Expression:

PIC1265HP1R0MF

(a) (b) (c) (d) (e)(f)

- a) Series Code
- b) Dimension Code
- c) Type Code
- d) Inductance Code
- e) Tolerance Code
- f) RoHS Compliant

2. Configuration & Dimensions:



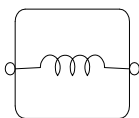
Note:

1. The above PCB layout is for reference only.
2. Solder paste thickness of 0.15mm and above is recommended.
3. Marking : Top row – Inductance code, Bottom row – Year/World week.

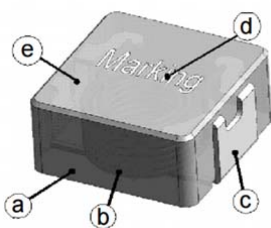
Unit: mm

A	B	C	D	E	L	G	H
13.5±0.5	12.5±0.3	6.2±0.3	2.3±0.3	4.7±0.3	14.2 Ref.	8.0 Ref.	5.0 Ref.

3. Schematic:



4. Material List:



- a) Core
- b) Wire
- c) Clip
- d) Ink
- e) Paint

NOTE: Specifications subject to change without notice. Please check our website for latest information.



5. General Specification:

- (a) Operating Temp. : -40°C to +125°C (Including self - temperature rise).
- (b) Storage Temp. : -40°C to +125°C (on board).
- (c) Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C.
- (d) Saturation Current (Isat) will cause L0 to drop approximately 30%.
- (e) Part Temperature (Ambient+Temp. Rise). : Should not exceed 125°C under worst case operating conditions.
- (f) Humidity Range. : 85 \pm 2% RH.
- (g) Storage Condition (Component in its packaging).
 - i) Temperature: Less than 40°C.
 - ii) Humidity: 60% RH.

NOTE: Specifications subject to change without notice. Please check our website for latest information.



6. Electrical Characteristics:

Part Number	Inductance L0 (uH) $\pm 20\%$ @ 0 A	Test Frequency (Hz)	I rms (A) Typ.	I sat (A) Typ.	DCR (m Ω) Typ.	DCR (m Ω) Max.
PIC1265HPR15MF	0.15	1.0V100K	55.0	118	0.49	0.60
PIC1265HPR22MF	0.22	1.0V100K	53.0	112	0.47	0.60
PIC1265HPR30MF	0.30	1.0V100K	48.0	72.0	0.60	0.72
PIC1265HPR33MF	0.33	1.0V100K	46.0	68.0	0.65	0.80
PIC1265HPR36MF	0.36	1.0V100K	45.0	66.0	0.70	0.90
PIC1265HPR40MF	0.40	1.0V100K	44.0	64.0	0.70	1.00
PIC1265HPR45MF	0.45	1.0V100K	42.0	63.0	0.90	1.20
PIC1265HPR47MF	0.47	1.0V100K	41.0	63.0	0.90	1.20
PIC1265HPR50MF	0.50	1.0V100K	40.0	60.0	0.92	1.25
PIC1265HPR56MF	0.56	1.0V100K	37.0	58.0	1.05	1.20
PIC1265HPR68MF	0.68	1.0V100K	35.0	55.0	1.25	1.50
PIC1265HPR82MF	0.82	1.0V100K	33.0	50.0	1.50	1.90
PIC1265HP1R0MF	1.00	1.0V100K	30.0	48.0	1.70	2.30
PIC1265HP1R5MF	1.50	1.0V100K	27.0	45.0	2.50	3.00
PIC1265HP1R8MF	1.80	1.0V100K	24.0	40.0	3.60	4.00
PIC1265HP2R2MF	2.20	1.0V100K	22.0	37.0	3.80	4.20
PIC1265HP2R7MF	2.70	1.0V100K	20.0	32.0	4.30	5.50
PIC1265HP3R3MF	3.30	1.0V100K	18.0	30.0	5.70	6.80
PIC1265HP4R7MF	4.70	1.0V100K	13.5	28.0	7.00	8.40
PIC1265HP5R6MF	5.60	1.0V100K	12.5	23.0	8.50	10.0
PIC1265HP6R8MF	6.80	1.0V100K	11.5	18.0	9.50	11.5
PIC1265HP7R0MF	7.00	1.0V100K	11.2	17.7	10.0	12.3
PIC1265HP8R2MF	8.20	1.0V100K	10.5	16.0	12.0	15.5
PIC1265HP100MF	10.0	1.0V100K	10.0	15.5	13.2	16.5
PIC1265HP120MF	12.0	1.0V100K	9.50	14.0	16.0	20.0
PIC1265HP130MF	13.0	1.0V100K	9.00	13.0	21.0	24.0
PIC1265HP150MF	15.0	1.0V100K	9.00	12.5	23.2	28.0
PIC1265HP220MF	22.0	1.0V100K	9.00	12.0	32.5	37.0
PIC1265HP330MF	33.0	1.0V100K	8.00	11.0	48.0	58.0
PIC1265HP470MF	47.0	1.0V100K	6.50	9.50	76.0	90.0
PIC1265HP101MF	100	1.0V100K	2.50	3.50	180	200

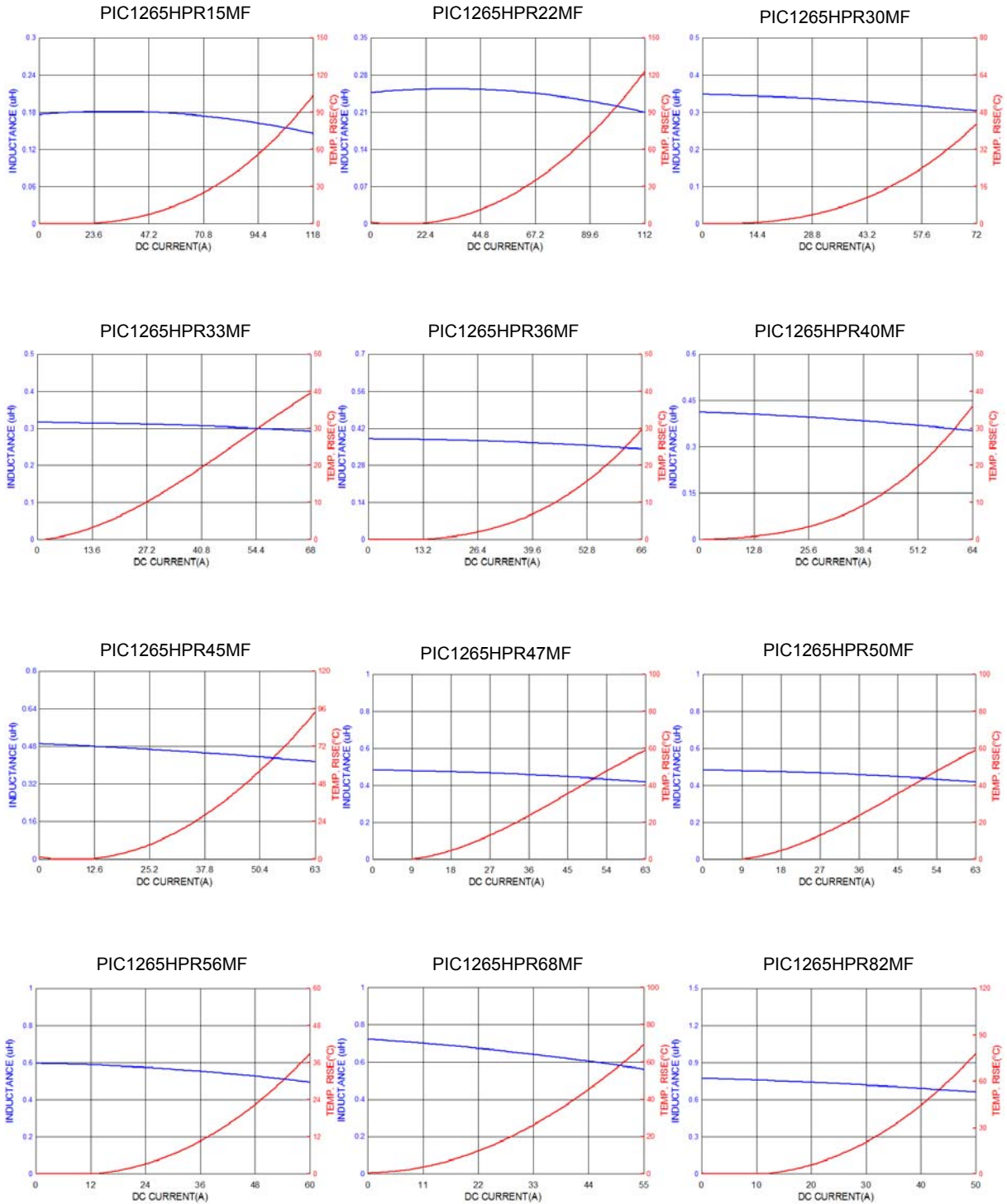
Notes:

1) Isat Typ. and Irms Typ. value is derived based from accounting the upper limit tolerance into the inductance value.

NOTE: Specifications subject to change without notice. Please check our website for latest information.

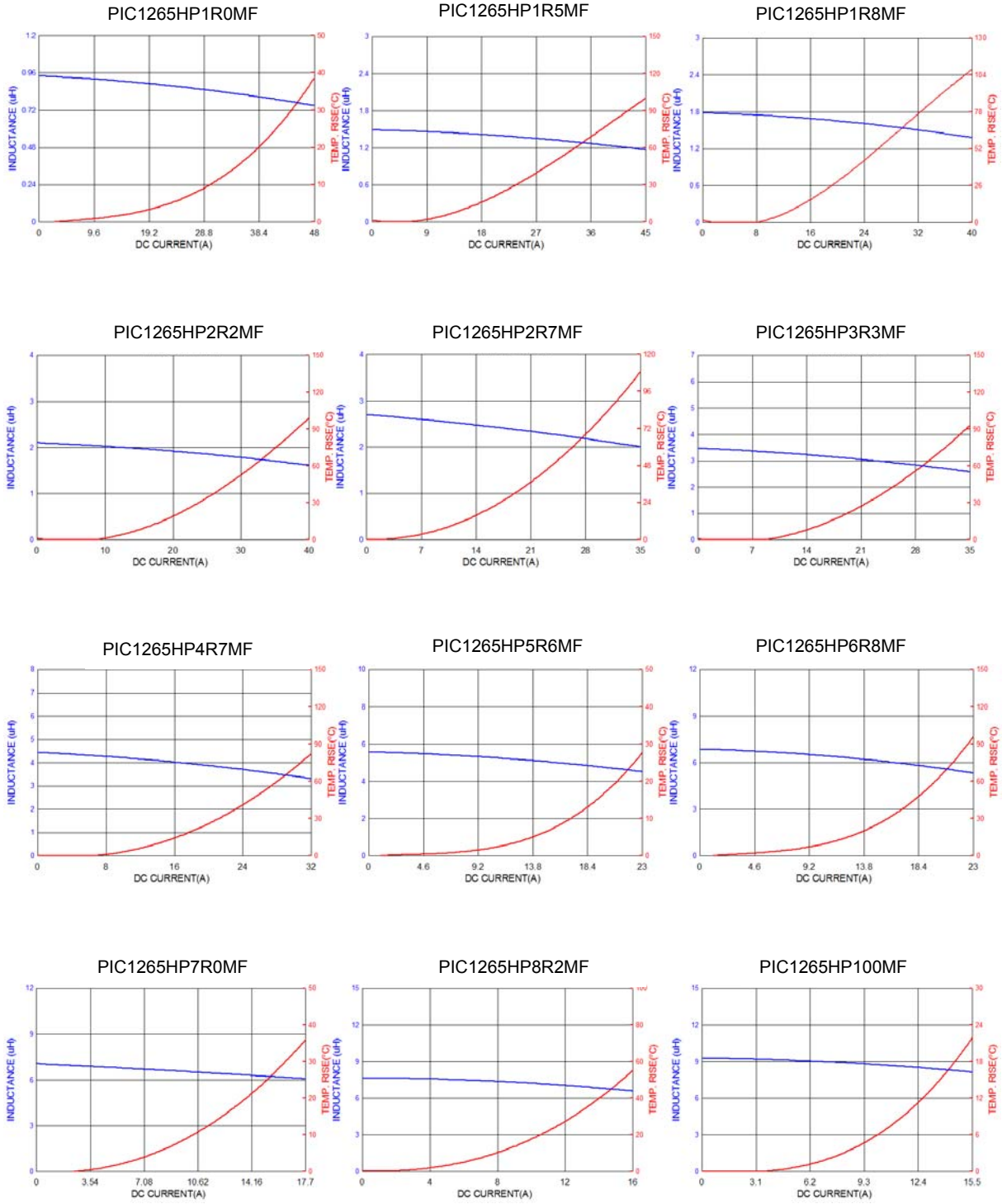


7. Characteristics Curves:

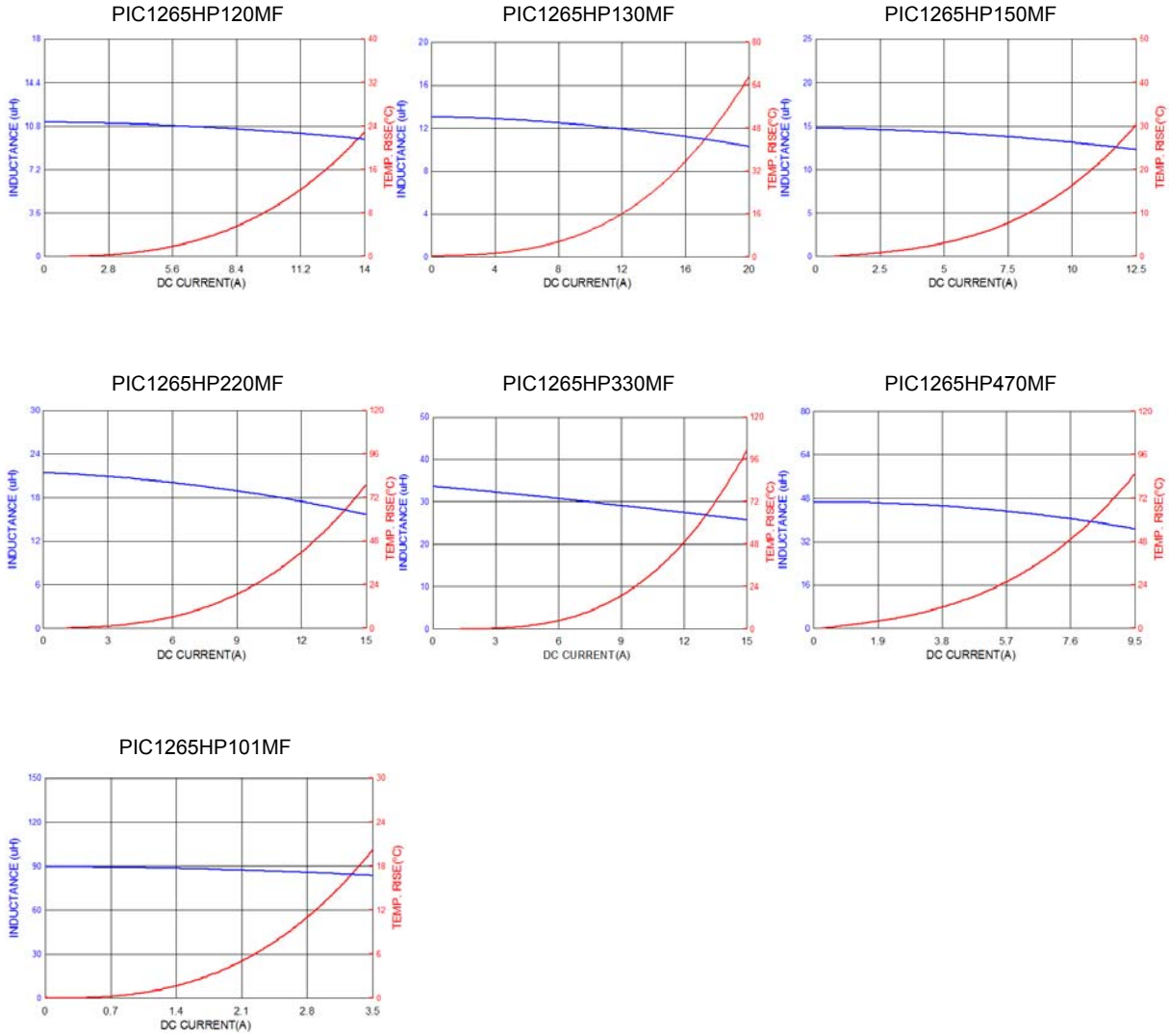


NOTE: Specifications subject to change without notice. Please check our website for latest information.





NOTE: Specifications subject to change without notice. Please check our website for latest information.



NOTE: Specifications subject to change without notice. Please check our website for latest information.



8. Soldering:

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air.

8-1 Solder Re-flow:

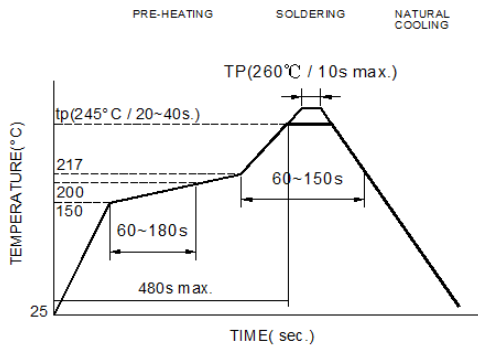
Recommended temperature profiles for re-flow soldering in Figure 1.

8-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

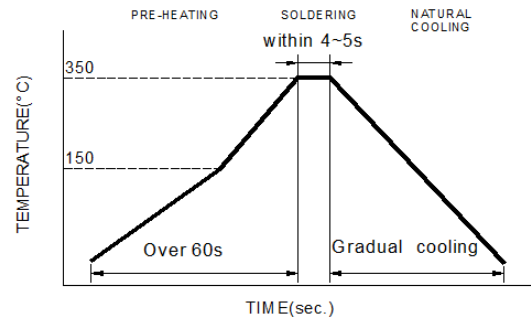
Note :

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.



Reflow times: 3 times max.

Fig.1



Iron Soldering times: 1 times max.

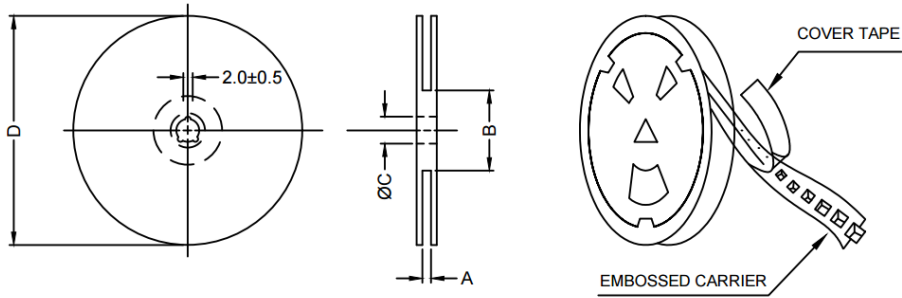
Fig.2

NOTE: Specifications subject to change without notice. Please check our website for latest information.



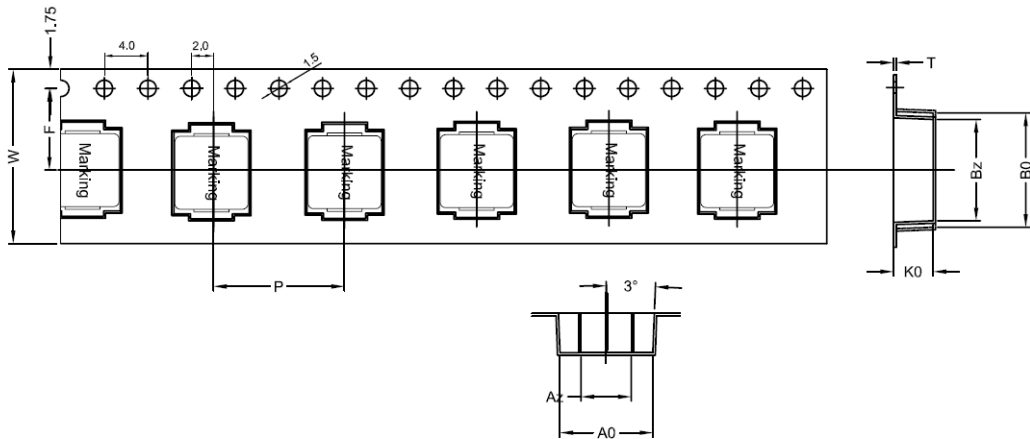
9. Packaging Information:

9-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	24.4+2/-0	100±2	13.0+0.5/-0.2	330

9-2 Tape Dimension



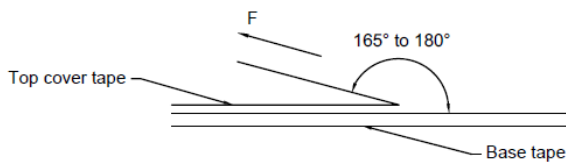
Series	Size	Bo(mm)	Bz(mm)	Ao(mm)	Az(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	T(mm)
PIC	1265	14.1±0.1	13.0±0.1	12.9±0.1	7.0±0.1	7.0±0.1	16.0±0.1	24.0±0.3	11.5±0.1	0.35±0.05

NOTE: Specifications subject to change without notice. Please check our website for latest information.

9-3 Packaging Quantity

PIC	1265
Chip / Reel	500
Inner box	1,000
Carton	4,000

9-4 Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

NOTE: Specifications subject to change without notice. Please check our website for latest information.

